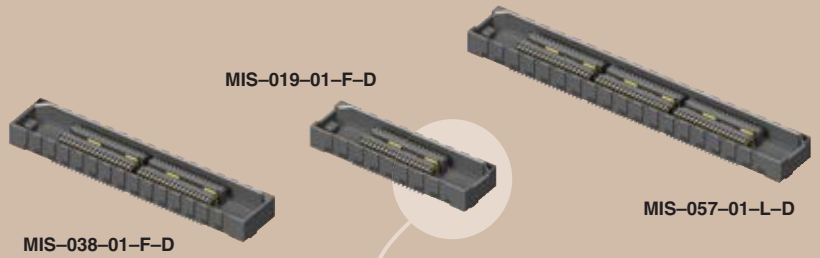




(0,635 mm) .025"

MIS SERIES



# MIXED TECHNOLOGY SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MIS](http://www.samtec.com?MIS)

**Insulator Material:**

Liquid Crystal Polymer



**Contact Material:**

Phosphor Bronze

**Plating:**

Au or Sn over

50µ" (1,27 µm) Ni

**Current Rating:**

Contacts: 1.6A per contact @ 80°C

Ground Plane: 8.7A per ground plane @ 80°C

**Operating Temp Range:**

-55°C to +125°C

**Voltage Rating:**

275 VAC

**Max Cycles:**

100

**RoHS Compliant:**

Yes

**Processing:**

Lead-Free Solderable:

Yes

**SMT Lead Coplanarity:**

(0,10 mm) .004" max (019-057)

**Board Stacking:**

For applications requiring more than two connectors per board contact [ipg@samtec.com](mailto:ipg@samtec.com)

**Board Mates:**  
MIT

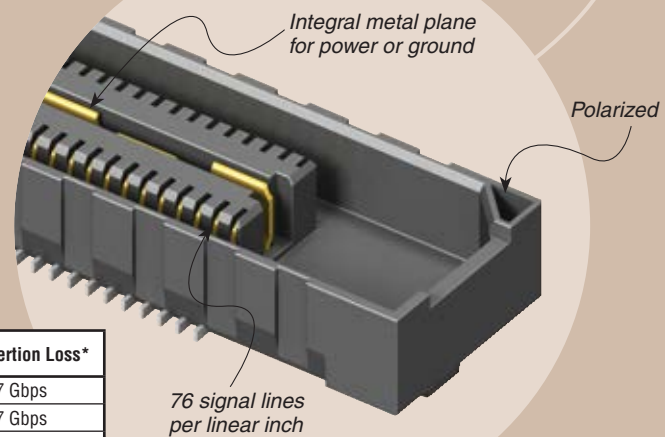
**Cable Mates:**  
MICD



• Mixed technology footprint

MIT/MIS 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps

\*Performance data includes effects of a non-optimized PCB. Performance data for other stack heights and complete test data available at [www.samtec.com?MIS](http://www.samtec.com?MIS) or contact [sig@samtec.com](mailto:sig@samtec.com)



## ALSO AVAILABLE

Board Spacing Standoffs. See SO Series.

## APPLICATION SPECIFIC OPTION

- 11 mm, 16 mm, 18,75 mm and 22 mm stack height
  - 30µ" (0,76 µm) Gold
  - Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
  - 76, 95, 114 and 133 positions per row
  - Edge Mount
- Call Samtec.



**-019, -038, -057**  
(38 total positions per bank)

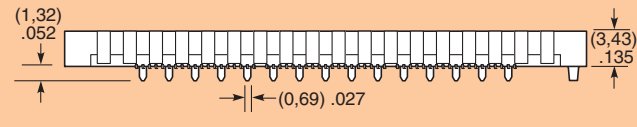
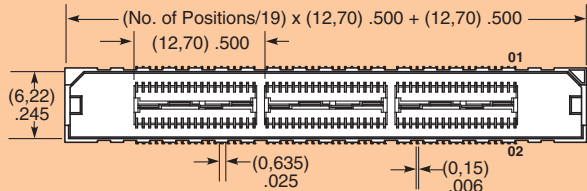
**-F**  
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

**-L**  
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

**-C\***  
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

**-K**  
= (7,00 mm) .275" DIA Polyimide film Pick & Place Pad

**-TR**  
= Tape & Reel



**Note:** Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press fit) for added retention to PCB.

*Due to technical progress, all designs, specifications and components are subject to change without notice.*

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)